

## LO566TBG4-60H-A1

### Features

All Plastic Mold Type  
High Luminous Intensity  
Low Current Requirement

### Applications

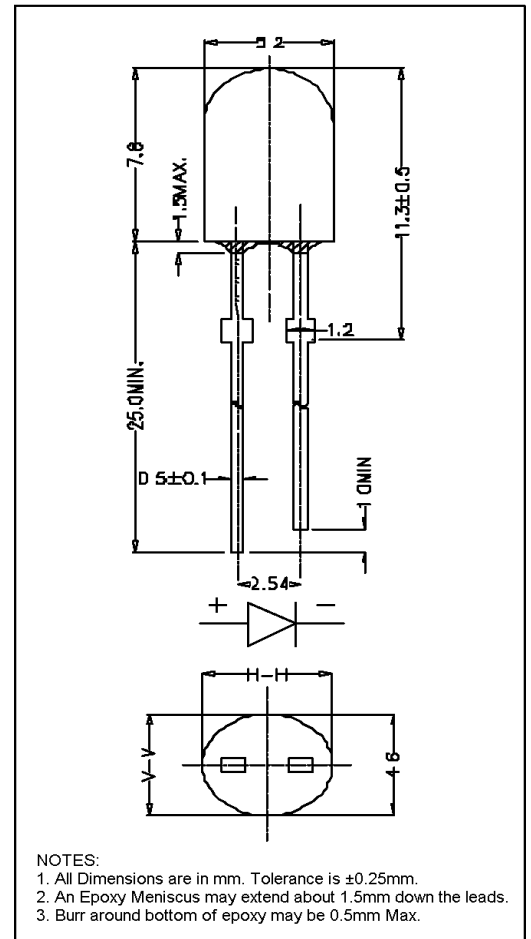
Backlighting  
Full Color/RGB Video Signs  
VMS  
Time/Temperature Boards

### Maximum Ratings (Ta=25°C)

Characteristic	Symbol	Max.	Unit
Forward Current	I <sub>F</sub>	25	mA
Reverse Voltage	V <sub>R</sub>	5	V
Power Dissipation	P <sub>D</sub>	100.00	mW
Operating Temperature	T <sub>opr</sub>	-40 ~ +95	°C
Storage Temperature	T <sub>stg</sub>	-40 ~ +100	°C
Soldering Temperature	T <sub>sol</sub>	260	°C
Soldering Time	-	for 3 sec. max	-

### Opto-Electrical Characteristics (Ta=25°C)

Characteristic	Symbol	Test Condition	Min	Typ	Max	Unit
Forward Voltage	V <sub>F</sub>	I <sub>F</sub> =20mA	-	3.40	4.00	V
Reverse Current	I <sub>R</sub>	V <sub>R</sub> =5V	-	-	100	μA
Luminous Intensity	I <sub>v</sub>	I <sub>F</sub> =20mA	1520.00	2200.00	-	mcd
Viewing Angle	2θ <sup>1/2</sup>	-	-	60° x 35°	-	deg.
Peak Wavelength	λ <sub>p</sub>	I <sub>F</sub> =20mA	-	520	-	nm
Dominant Wavelength	λ <sub>d</sub>	I <sub>F</sub> =20mA	-	525	-	nm
Spectral Line Half Width	Δλ	I <sub>F</sub> =20mA	-	38	-	nm



## LO566TBG4-60H-A1 Graphs

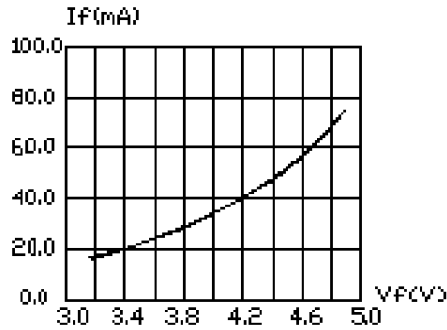


FIG.1 FORWARD CURRENT VS. FORWARD VOLTAGE

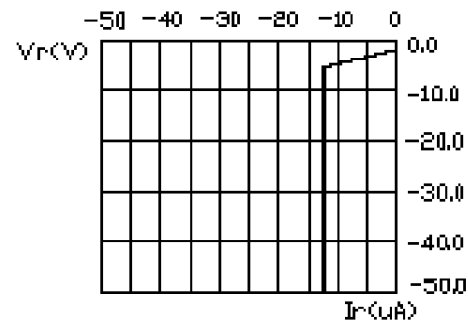


FIG.2 REVERSE CURRENT VS. REVERSE VOLTAGE

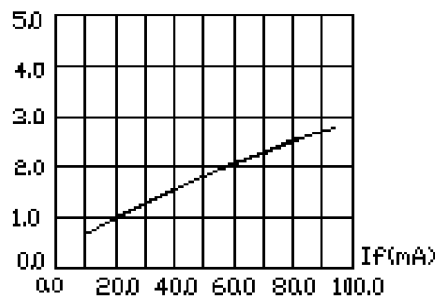


FIG.3 RELATIVE LUMINOUS INTENSITY VS. FORWARD CURRENT

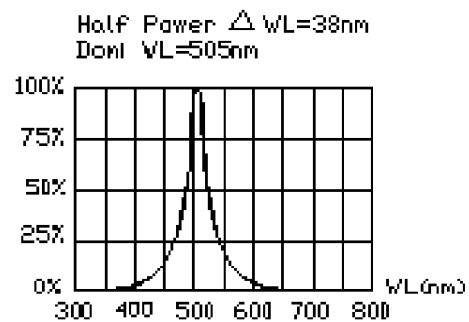


FIG.4 RELATIVE LUMINOUS INTENSITY VS. WAVELENGTH

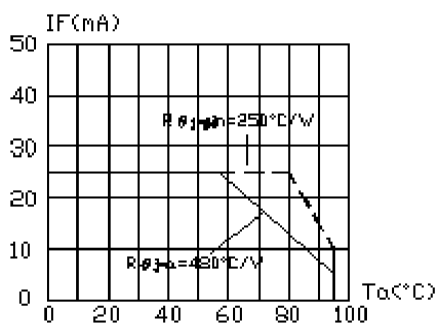


FIG.5 MAXIMUM FORWARD CURRENT VS. AMBIENT TEMPERATURE ( $T_{jmax}=105^{\circ}C$ )

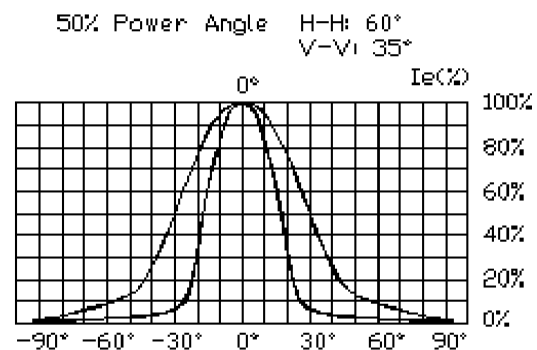


FIG.6 FAR FIELD PATTERN

1. Cathode PAD Area (0.18 X 0.18inch<sup>2</sup>)
2. Height above nominal seating plane in inches(0.3inch)